Serial Number: 09/800,703 Filing Date: March 7, 2001

Title: CHIP PACKAGE WITH DEGASSING HOLES

Assignee: Intel Corporation

REMARKS

The specification has been amended to update the priority information, specifically to include the patent number of the issued parent case. It is respectfully submitted that this change does not introduce new matter, and the claims are allowable without further search or consideration. Therefore, entry is appropriate under Rule 312, and is respectfully requested.

Respectfully submitted,

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Page 3

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this _____ day of August, 2004.